

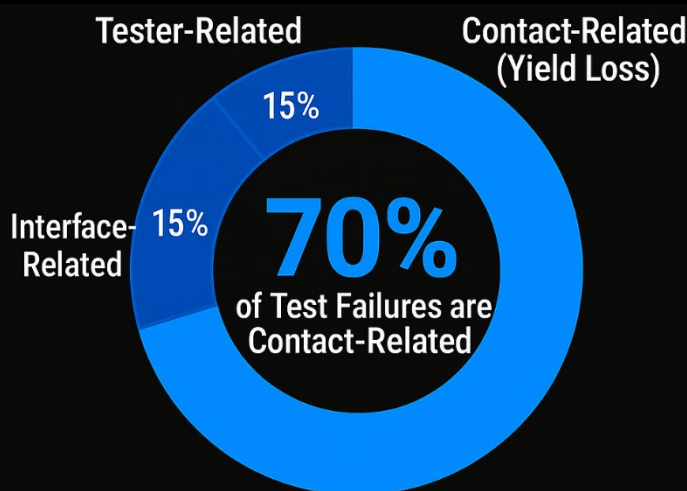
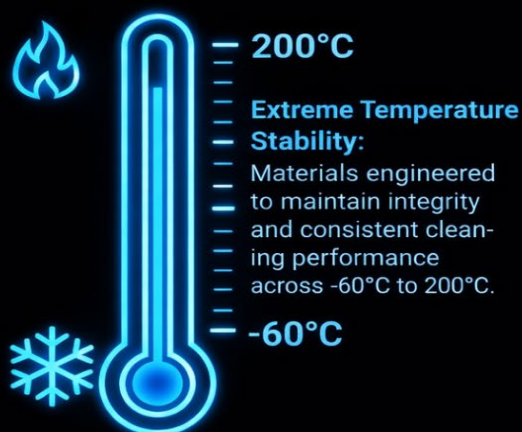
MAXIMIZE WAFER TEST YIELD & EXTEND PROBE CARD LIFE

Your Innovation Partner for Test Efficiency: Our Gel-Probe™ line elevates probe cleaning with advanced material science and precision engineering — removing debris, improving CRES performance, and protecting delicate probe tips. The result: cleaner contacts, higher test efficiency, and more reliable results.

Prolong Probe Card Life: *Non-Destructive Cleaning.* Our proprietary elastomer exerts force only in the Z-direction (vertical), ensuring no lateral stress is applied to the tips. This non-destructive action effectively cleans without compromising the structural integrity of the probe, extending the lifespan of your probe card.

Improve Test Yield & Accuracy: *Stabilize CRES Eliminate Debris.* Test engineering demands a "perfect" contact. Gel-Probe maximizes manufacturing efficiency by removing debris that affects test program performance and stabilizing parametric CRES. Gel-Probe increases prober availability and ensures accurate probe-to-pad alignment (PTPA), directly contributing to higher test yields.

Superior High-Temperature Performance: *Reliability. From 60°C to +200°C.* Whether testing in cold or extreme heat, Gel-Probe delivers consistent cleaning performance.



Stabilize CRES & Eliminate Debris:

Maximizes efficiency by removing contaminants and stabilizing parametric Contact Resistance (CRES).

Unmatched Material Science Expertise: *45 Years of Elastomer Innovation.* Gel-Pak is more than a manufacturer; we are a team of chemists and engineers dedicated to solving complex challenges. With decades of experience in elastomer technologies, we customize formulation and processing conditions to meet the requirements of today's leading test companies.

Gel-Probe vs. Competition

Feature	Gel-Probe	Competition
Surface Texture	Uniform for Optical Recognition	Variable and Inconsistent
Substrate	Polyimide (-60°C to 200°C)	Polyester (Limited to 105°C)
Outgassing	Meets/Exceeds ASTM E595	Unknown/ Not Rated

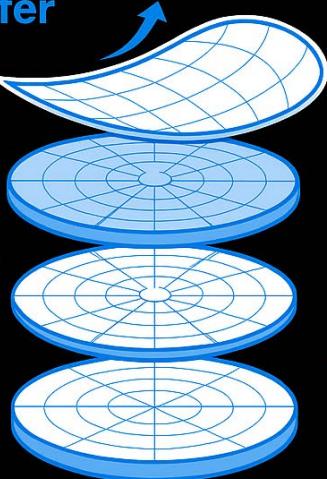
Gel-Probe Wafer

Cover Sheet
 PEEL OFF PRIOR TO USE

Cleaning Elastomer
 UNFILLED / FILLED

Bond Layer
 HIGH TEMP ADHESIVE

Silicon Wafer
 200 mm / 300 mm



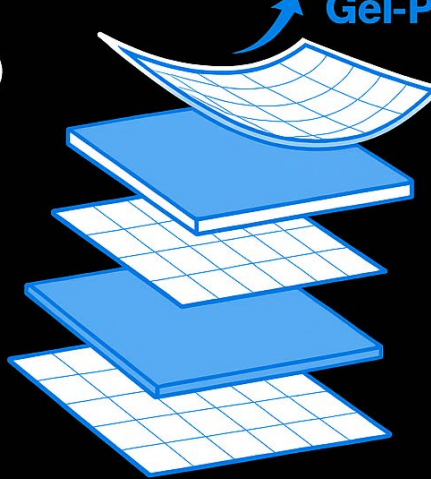
Gel-Probe Sheets

Cover Sheet
 PEEL OFF PRIOR TO USE

Cleaning Elastomer
 UNFILLED / FILLED

Polyimide
 HIGH TEMP CARRIER

PSA
 HIGH TEMP ADHESIVE



FEATURE	GEL-PROBE REFINE	GEL-PROBE REMOVE	GEL-PROBE RECOVER
Primary Function	Polishing & Debris Removal	Debris Removal	Cleaning, Polishing, & Reshaping
Material Composition	Proprietary Gel Elastomer Blended with Abrasive Particles	Proprietary Non-Abrasive Gel Elastomer	Proprietary Gel Elastomer Blended with Abrasive Particles
Abrasive Loading	L3, M3, H3, U3, H5, H10	N/A	U5, U10
Available Form Factors	Sheets, 200mm & 300mm Wafer	Sheets, 200mm & 300mm Wafer	Sheets, 200mm & 300mm Wafer
Operating Temperature	-60°C - 200°C	-60°C to 200°C	-60°C to 200°C